

Report NO: 10E080014

EMB-9459T

Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> Pass <input type="checkbox"/> Fail <input type="checkbox"/> Pass with Deviation Comment: _____				
	Test Result Summary				
	Critical	Major	Minor	Enhancement	
Defect Found	0	0	0	0	
Defect Unsolved	0	0	0	0	

Issue date

2010/09/29

Approval

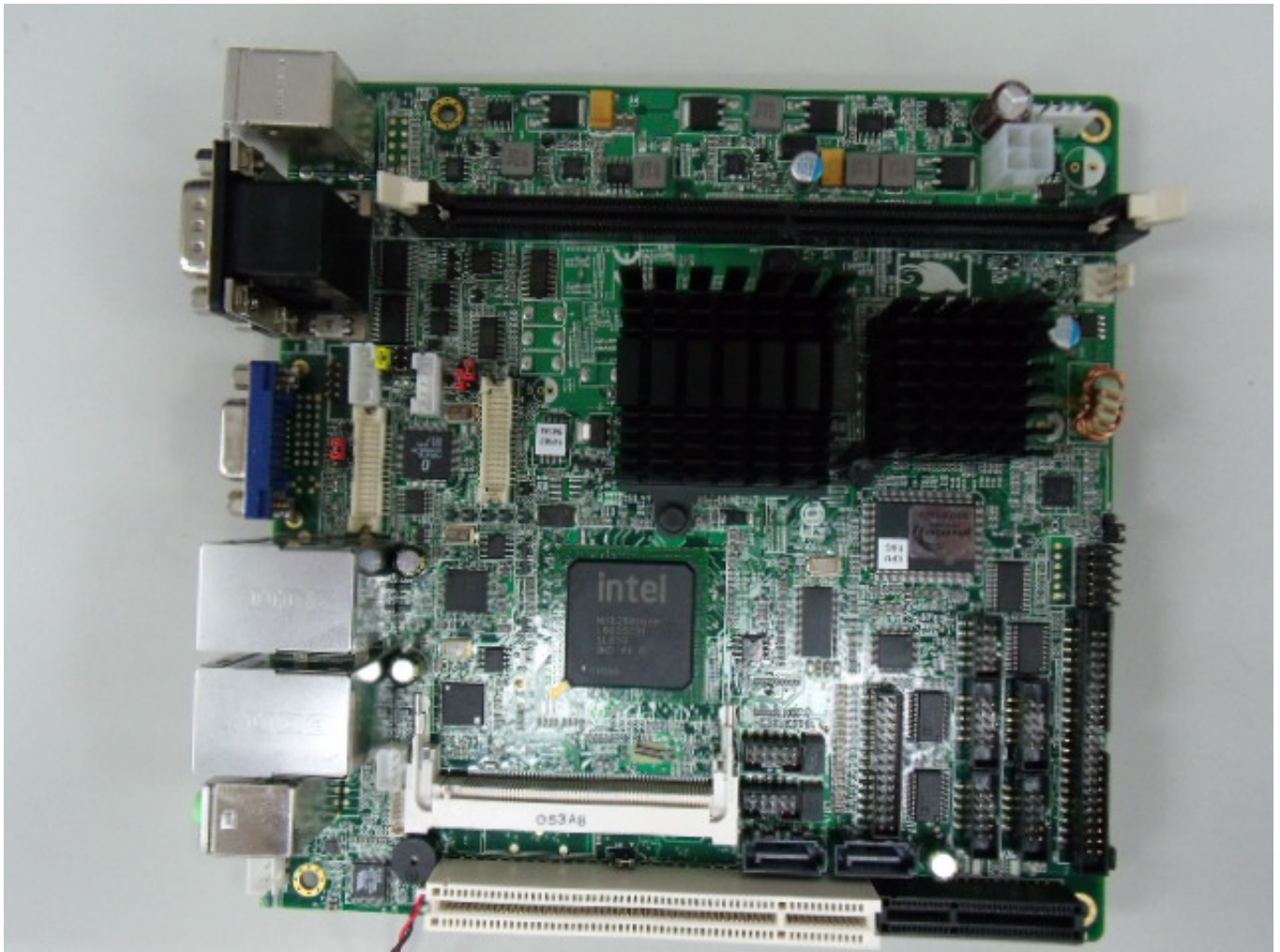
Jansin Lee

Test Engineer

Anderson Lin

Sample Configuration & Quantity Under Test

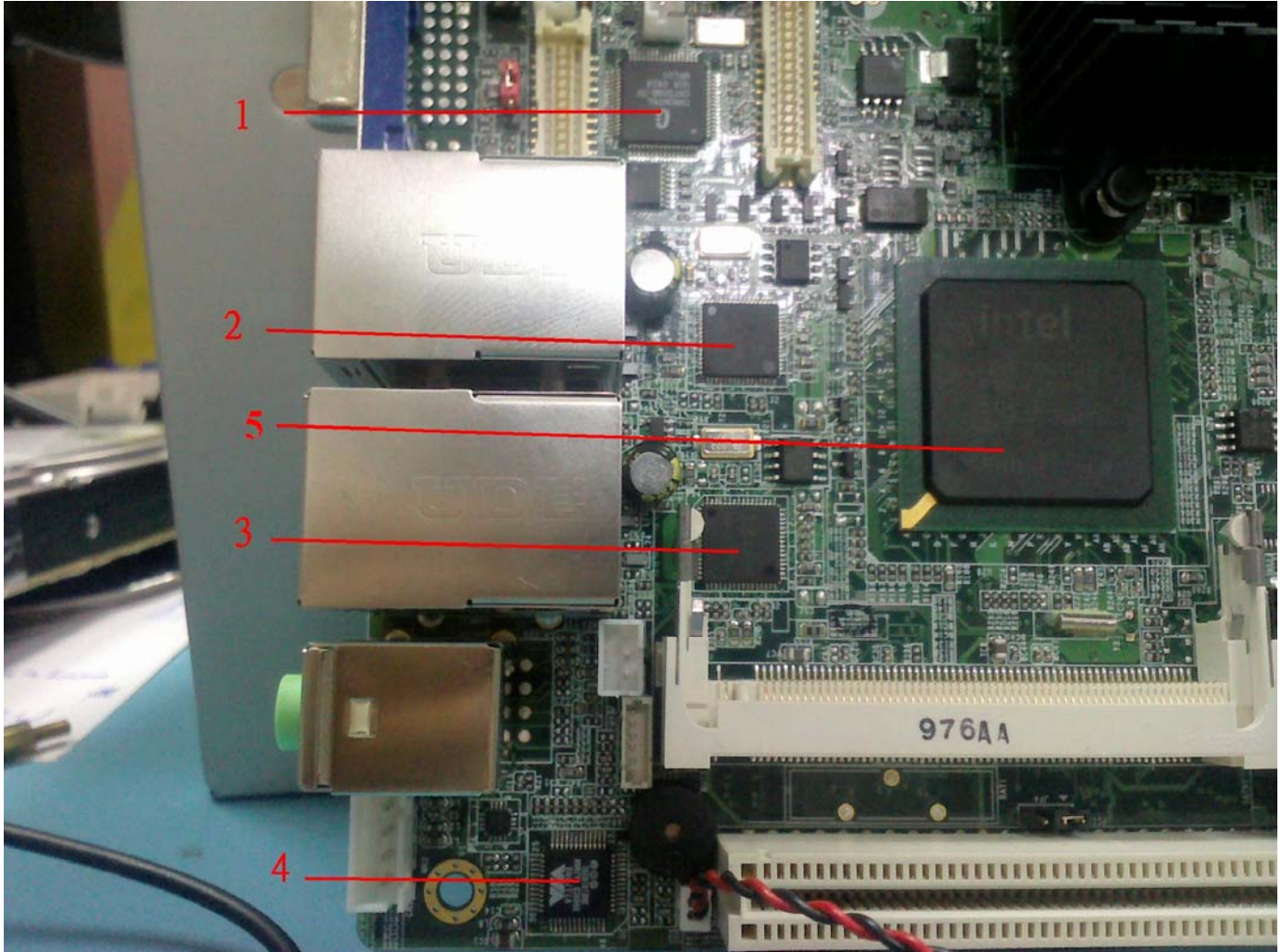
- CPU Board: EMB-9459T Rev:A2.0
- Carrier Board:N/A
- CPU: Intel Atom N270 1.60GHz
- Memory: Kingston 1GB DDR2 800(KVR800D2N6)
- HDD: WD 3.5" SATA3 H.D / WD6402AAEX
- BIOS : EMB-9459T-A20 BIOS Rev 2.0 (06/10/2010)
- Test Software: Windows XP sp3 / Run Prime95 v25.9
- AT Power Supply: ZECK ZKS-300W
- Cooler:

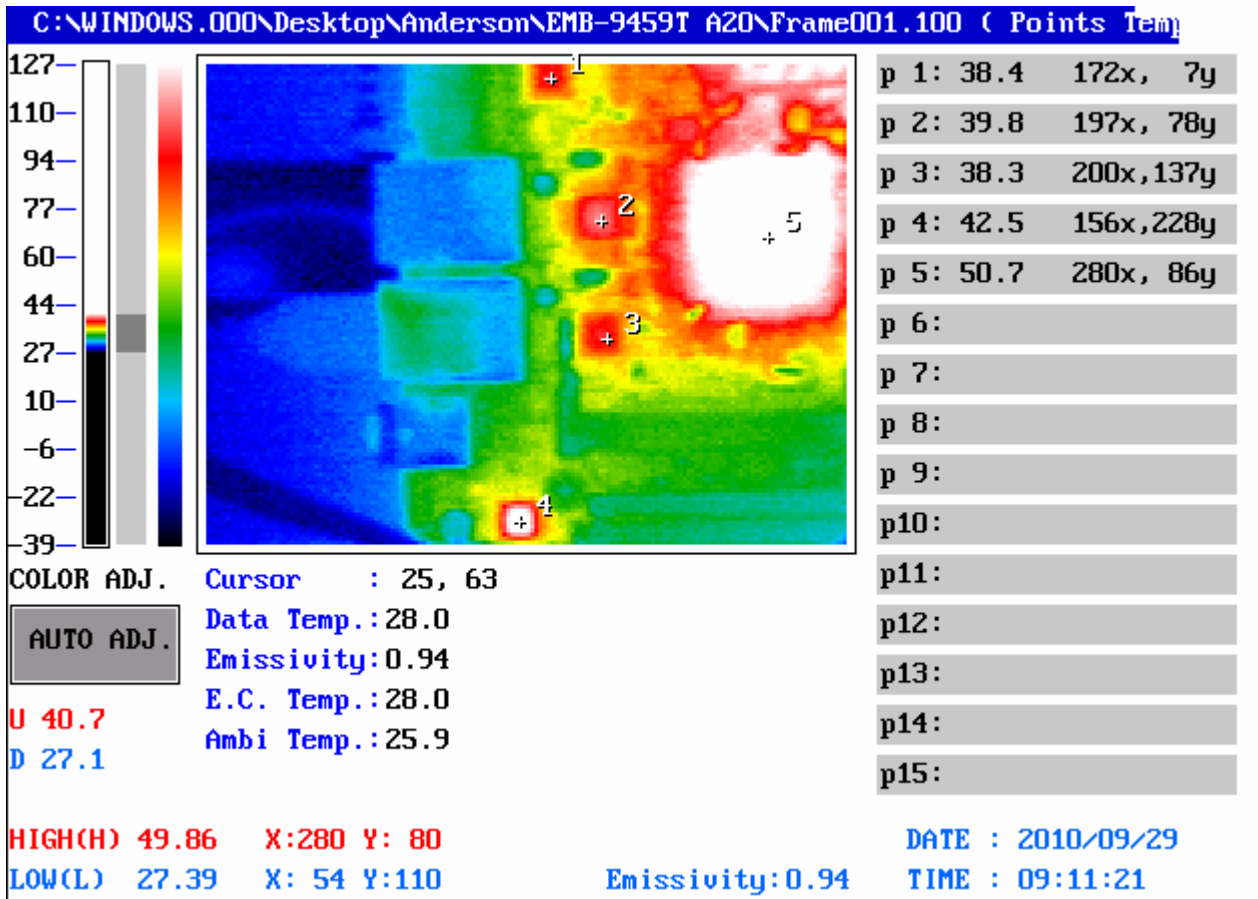


Thermal Image Analysis

1. Test Date: 09/29/2010
2. Test Product: EMB-9459T
3. Test Site: AAEON QA Internal Lab.
4. Temperature Measurement:
MR-1000(TH-046)
5. Test Condition:
Component Side-1: 25.9°C
Component Side-2: 26.4°C
Component Side-2: 24.1°C
6. Test Software:
Windows XP sp3 / Run Prime 95 v25.9
7. Take Picture Time:
After running Prime 95 for 2 hours

**Temperature Profile Test:
Component Side-1:**





Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.9°C	60°C	
1	U49	(TF)IC.SMD.LQFP 64Pin.LVDS Transmitter.CHRONTEL.CH7308B-TF	115	38.4	72.5	
2	U17	(TF)IC.SMD.QFN.64P.PCI-express.Gigabit Ethernet Chip.REALTEK.RTL8111C-VB-GR	100	39.8	73.9	
3	U18	(TF)IC.SMD.QFN.64P.PCI-express.GigabitEthernet Chip.REALTEK.RTL8111C-VB-GR	100	38.3	72.4	

4	U2	(TF)IC.SMD.LQFP Codec.VIA.VT1708B	48P.7.1Channel	HD	Audio	85	42.5	76.6	
5	U28	(TF)IC.SMD.Chipset ICH7M.Intel.NH82801GBM SL8YB				100	50.7	84.8	

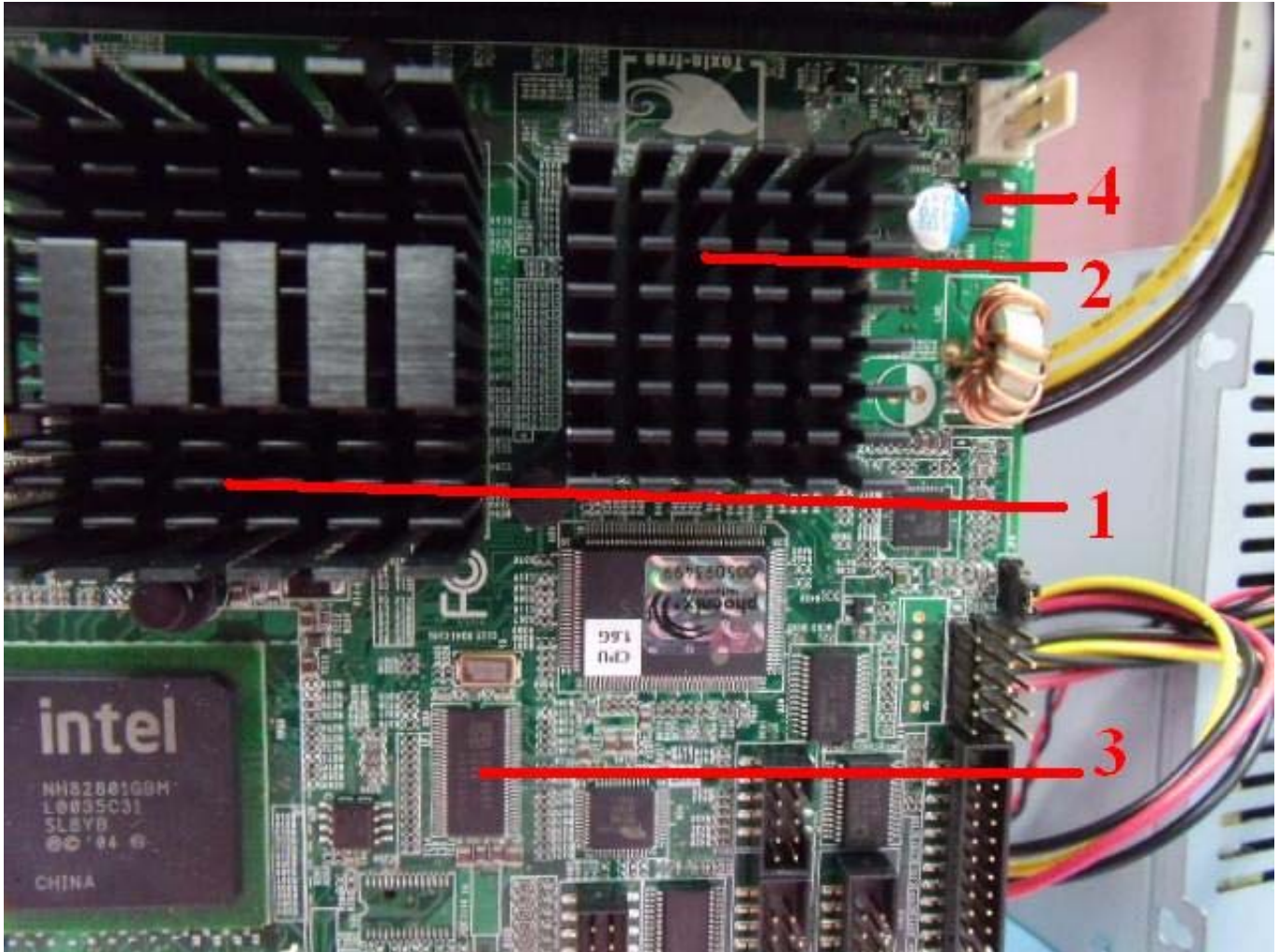
Note(*):

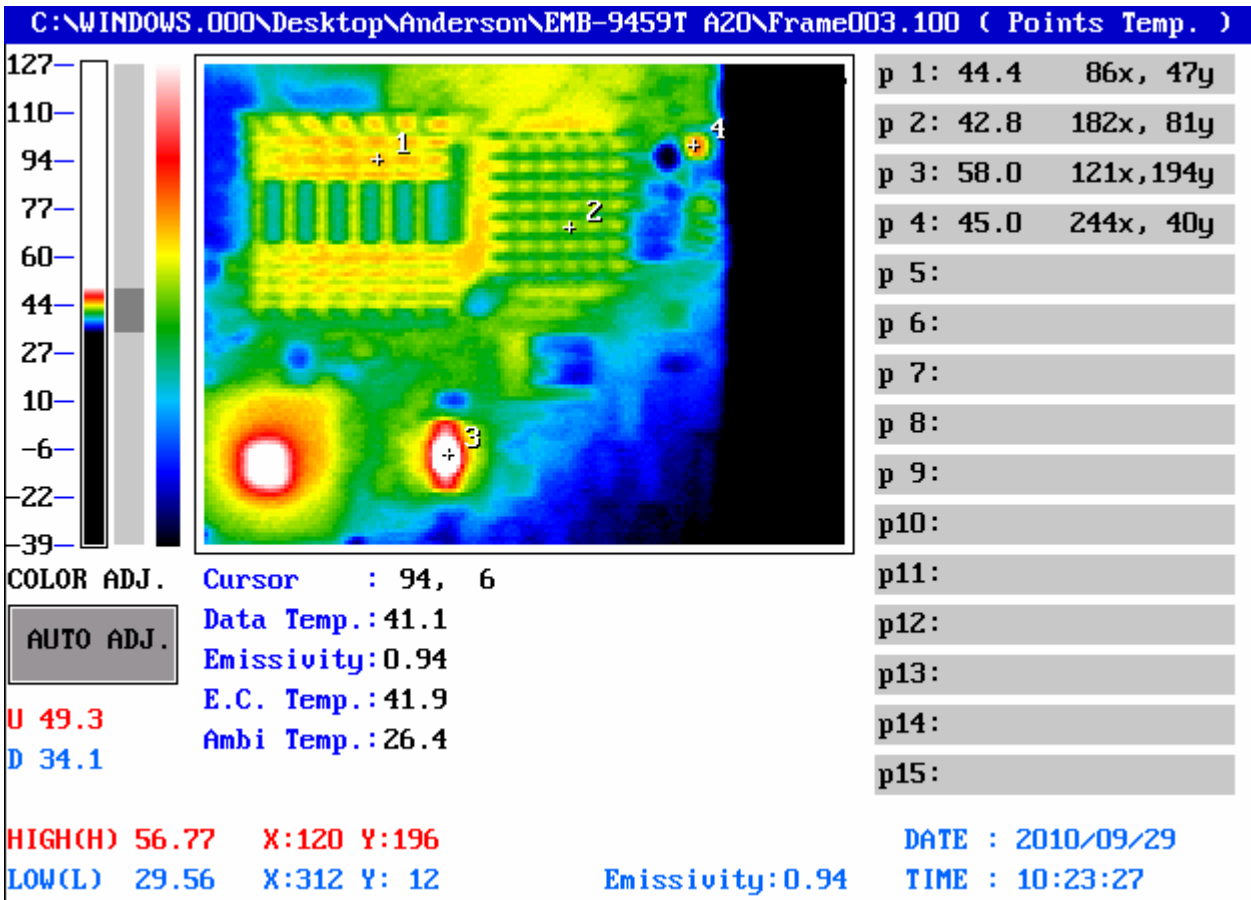
1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
- **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.

Component Side-2:

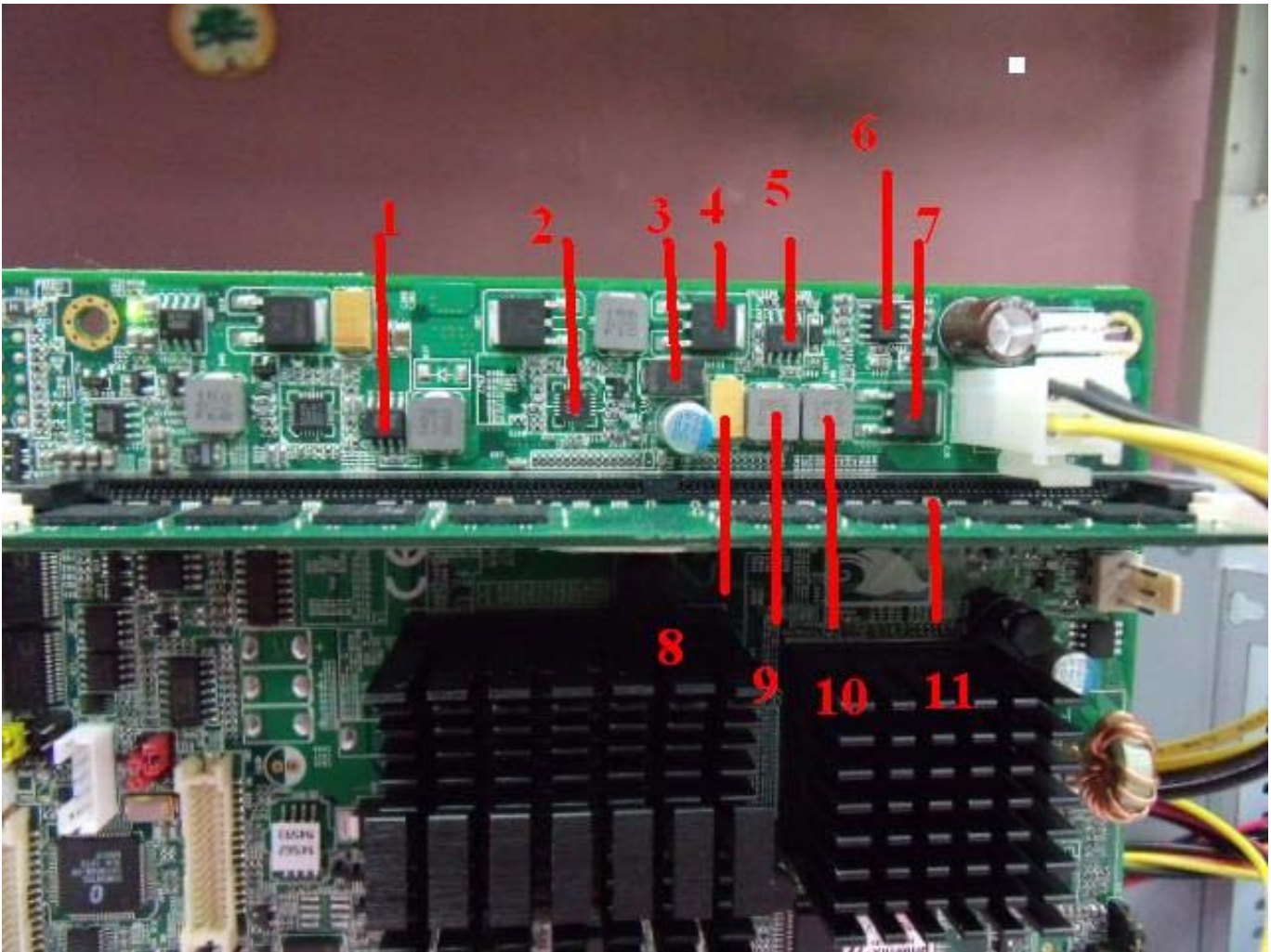


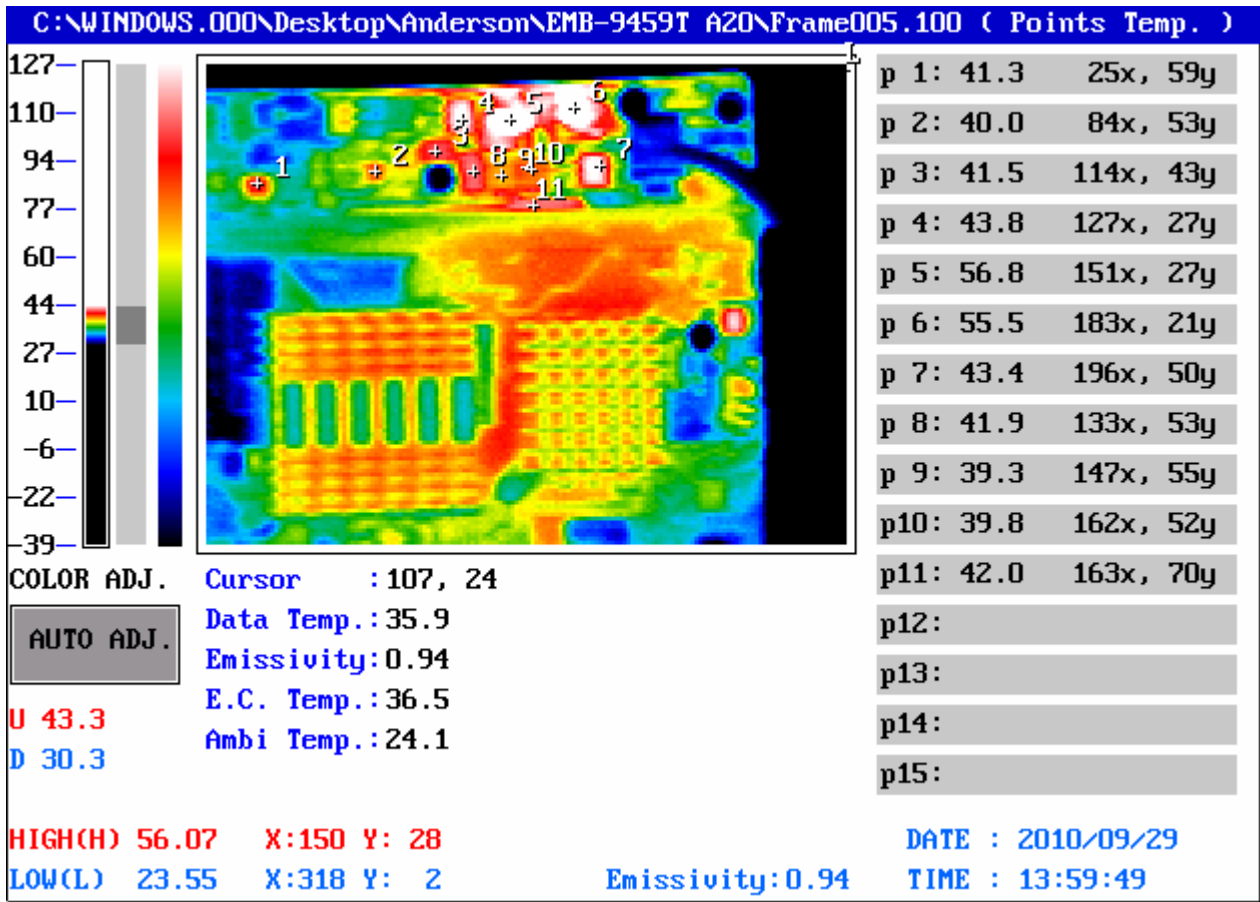


Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				26.4°C	60°C	
1	U30(NB)	(TF)IC.SMD.Intel 945GSE Express Chipset.Intel.QG82945GSE SLB2R	105	44.4	81.6	
2	U38(CPU)	(TF)Intel CPU.Diamondville.N270.1.6GHz/FSB 533MHz.FCBGA8.437Pins.STEPPING CODE:SLB73.AU80586GE025D	90	42.8	76.4	
3	U33	(TF)IC.SMD.TSSOP 56P.CLOCK GENERATOR.ICS.ICS954226AGLF	115	58.0	91.6	
4	Q66	(TF)Dual N-Channel.SO-8.SMD.Vds=60V.Vgs=(+/-)25V.Ids=7/5A.Rds=21/2 7mohm.APEC.AP9975GM	125	45.0	78.6	

Note(*):

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2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.
3. **Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
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 - **Pass** : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.

Component Side-3:



Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				24.1°C	60°C	
1	U27	(TF)IC.SMD MLPQ-24.Dual Synchronous Buck Control.Semtech.SC415MLTRT	100	41.3	77.2	
2	U53	(TF)IC.SMD MLPQ-24.DDR1/2/3 Memory Power Supply.Semtech.SC488MLTRT	125	40.0	75.9	
3	D46	(TF)D Schottky.SMD SOT-23.PHILIPS.BAT54C	100	41.5	77.2	
4	EC19	(TF)SP CAP.150uF.6.3V.20%.D(7.3*4.3*2.8mm).18mOhm SMD.Panasonic.ECGUD0J151ER	105	43.8	79.7	
5	U52	(TF)IC.SMD.SOP 8P.Switching PWM Controller.Richtek.RT9214PS	125	56.8	92.7	
6	U55	(TF)IC.SMD.SOP 8P.Switching PWM Controller.Richtek.RT9214PS	125	55.5	91.4	
7	Q72	(TF)PWR.SMD.TO-252.30V 94A.N-channel Power MOSFET.FAIRCHILD.FDD8896_NL	150	43.4	79.3	
8	EC5	(TF)KO-CAP.220uF.6.3V.20%.D(7.3*4.3*1.9mm).40mOhm SMD.KEMET.T520V227M006AS	135	41.9	77.8	

9	L66	(TF)COIL.3.3uH.SMD.7.3*6.8*3.0mm.DCR=28m ohm.Irms=6Amp.GOTREND.GSTC063P-3R3MN	155	39.3	75.2	
10	L80	(TF)COIL.3.3uH.SMD.7.3*6.8*3.0mm.DCR=28m ohm.Irms=6Amp.GOTREND.GSTC063P-3R3MN	155	39.8	75.7	
11	DIMM1	Kingston 1GB DDR2 800(KVR800D2N6)	----	42.0	77.9	

Note(*):

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3. Judgment Criteria:

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- **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
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